

I. Power section

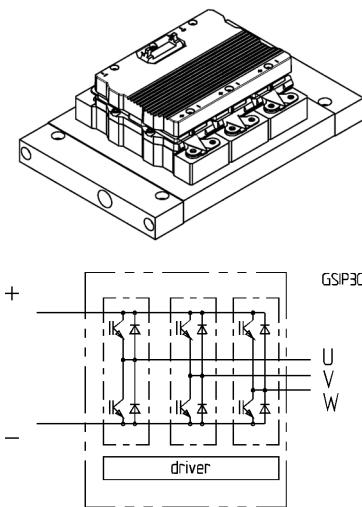
Absolute maximum ratings		$T_s = 25^\circ\text{C}$ unless otherwise specified		
Symbol	Conditions	Values	Units	
IGBT				
$V_{CES}^{(1)}$	Operating DC link voltage	600 400 ± 20	V V V	
V_{GES}		800 (600)	A	
I_c	$T_s = 25 \text{ (70) } ^\circ\text{C}$			
Inverse diode				
$I_F = -I_c$	$T_s = 25 \text{ (70) } ^\circ\text{C}$	800 (600)	A	
I_{FSM}	$T_j = 150 \text{ } ^\circ\text{C}, t_p = 10\text{ms}; \sin$	6000	A	
I^2t (Diode)	Diode, $T_i = 150 \text{ } ^\circ\text{C}, 10\text{ms}$	180	kA ² s	
$T_j, (T_{stg})$		-40...+150 (125)	°C	
V_{isol}	rms, AC, 1min	2500	V	
$I_{AC\text{-terminal}}$	per AC terminal, rms, $T_s = 70^\circ\text{C}, T_{\text{terminal}} < 115^\circ\text{C}$	400	A	

Characteristics $T_s = 25^\circ\text{C}$ unless otherwise specified				
Symbol	Conditions	min.	typ.	max.
IGBT				
V_{CEsat}	$I_c = 300\text{A}, T_j = 25 \text{ (125) } ^\circ\text{C};$ measured at terminal	-	1,5 (1,6)	1,8
V_{CEO}	$T_j = 25 \text{ (125) } ^\circ\text{C};$ at terminal	-	0,8 (0,7)	1,0 (0,9)
r_{CE}	$T_j = 25 \text{ (125) } ^\circ\text{C};$ at terminal	-	2,4 (3,1)	2,7 (3,4)
I_{CES}	$V_{GE}=0, V_{CE}=V_{CES}, T_j=25(125) \text{ } ^\circ\text{C}$	-	1,2 (36)	-
$E_{on} + E_{off}$	$I_c=300\text{A}, V_{cc}=300\text{V}$ $T_j=125^\circ\text{C}$	-	27	-
	$V_{cc}=400\text{V}$	-	39	-
L_{CE}	top, bottom	-	12	-
C_{CHC}	per phase, AC side	-	1,0	-
$R_{CC\text{-EE}}$	terminal-chip, $T_j=25 \text{ } ^\circ\text{C}$	-	0,50	-
Inverse diode				
$V_F = V_{EC}$	$I_F = 300\text{A}; T_j = 25(125) \text{ } ^\circ\text{C}$ measured at terminal	-	1,3 (1,2)	1,5
V_{TO}	$T_j = 25 \text{ (125) } ^\circ\text{C}$	-	0,8 (0,6)	1 (0,8)
r_T	$T_j = 25 \text{ (125) } ^\circ\text{C}$	-	1,5 (1,9)	1,7 (2,0)
E_{RR}	$I_c=300\text{A}, V_{cc}=300\text{V}$ $T_j=125^\circ\text{C}$	-	5	-
	$V_{cc}=400\text{V}$	-	6	-
Mechanical data				
M_{dc}	DC terminals, SI Units	6	-	8
M_{ac}	AC terminals, SI Units	13	-	15
w	SKiiP® 3 System w/o heat sink	-	2,4	-
w	heat sink	-	5,2	-
Thermal characteristics (NWK 40; 8l/min; 50%glyc.); "s" reference to heat sink; "r" reference to built-in temperature sensor (acc. IEC 60747-15)				
$R_{thjsIGBT}$	per IGBT	-	-	0,051
$R_{thjsdiode}$	per diode	-	-	0,100
Z_{th}	$R_i (\text{mK/W})$ (max. values)		tau _i (s)	
	1 2 3 4	1	2	3 4
$IGBT_{jr}$	4,2 20,4 23,4 0,0	69,0	0,350	0,02 1,0
diode _{jr}	7,8 12,0 53,1 53,1	50,0	5,0	0,25 0,04
heatsink _{ra}	4,6 4,7 1,1 0,6	48	15	2,8 0,4

SKiiP® 3**SK integrated intelligent Power 6-pack****SKiiP 803GD061-3DUW**

Preliminary data

Case S33

**Features**

- SKiiP technology inside
- low loss IGBTs
- CAL diode technology
- integrated current sensor
- integrated temperature sensor
- integrated heat sink
- IEC 60721-3-3 (humidity) class 3K3/IE32 (SKiiP® 3 System)
- IEC 68T.1 (climate) 40/125/56 (SKiiP® 3 power section)
- UL recognized File no. E63532 (SKiiP® 3 power section)

- 1) with assembly of suitable MKP capacitor per terminal (SEMIKRON type is recommended)

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SKiiP 803GD061-3DUW

SKiiP 3®

SK integrated intelligent Power

SKiiP 803GD061-3DUW

Preliminary data

Gate driver features

- CMOS compatible inputs
- wide range power supply
- integrated circuitry to sense phase current, heat sink temperature and DC-bus voltage (option)
- short circuit protection
- over current protection
- over voltage protection (option)
- power supply protected against under voltage
- interlock of top/bottom switch
- isolation by transformers
- fibre optic interface (option for GB-types only)
- IEC 68T.1 (climate) 40/85/56 (SKiiP® 3 gate driver)

II. Integrated gate driver

Absolute maximum ratings

Symbol	Term	Value	Unit
V_{S2}	unstabilized 24V power supply	35	V
V_{iH}	input signal voltage (high)	15 + 0,3	V
dv/dt	secondary to primary side	75	kV/μs
V_{isoIO}	input / output (AC, rms, 2 s)	2500	V
V_{isoIPD}	partial discharge extinction voltage, rms, $Q_{PD} \leq 10 \text{ pC}$;	960	V
V_{isol12}	output 1 / output 2 (AC, rms, 2s)	1500	V
f	switching frequency	20	kHz
T_{op} (T_{stg})	operating / storage temperature	- 40 ... + 85	°C

Electrical characteristics ($T_a = 25^\circ\text{C}$)

Symbol	Term	min	typ	max.	Units
V_{S2}	supply voltage non stabilized	13	24	30	V
I_{S2}	$V_{S2} = 24\text{V}$	$280 + 30*f/\text{kHz} + 0,00111 * (I_{AC}/A)^2$			mA
V_{iT+}	input threshold voltage (High)	11,2	—	—	V
V_{iT-}	input threshold voltage (Low)	—	—	5,4	V
R_{in}	input resistance	—	10	—	kΩ
C_{in}	input capacitance	—	1	—	nF
$t_{d(on)IO}$	input-output turn-on propagation time	—	1,1	—	μs
$t_{d(off)IO}$	input-output turn-off propagation time	—	1,1	—	μs
$t_{pERRRESET}$	error memory reset time	—	9	—	μs
t_{TD}	top/bottom switch: interlock time	—	3,3	—	μs
$I_{analogOUT}$	max. 5mA ; 8 V corresponds to 15 V supply voltage for external components; max load current	—	600	—	A
I_{S1out}		—	—	50	mA
I_{TRIPSC}	over current trip level ($I_{analog OUT} = 10\text{V}$)	—	750	—	A
T_{tp}	over temperature protection	110	—	120	°C
U_{DCTRIP}	U_{DC} -protection ($U_{analog OUT} = 9\text{V}$) (option for GB types)	400	—	—	V

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